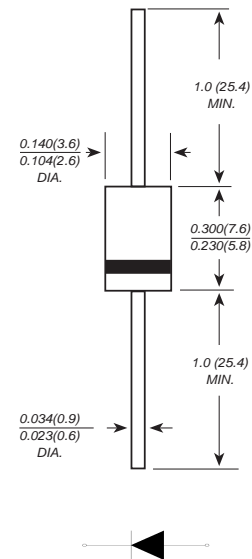


**Features**

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Open Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed  
260°C/10 seconds at terminals

**Mechanical Data**

- Case** : Molded plastic body  
**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity** : Polarity symbol marking on body  
**Mounting Position** : Any  
**Weight** : 0.0116 ounce, 0.33 grams



Dimensions in inches and (millimeters)

**Maximum Ratings And Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	2A01	2A02	2A03	2A04	2A05	2A06	2A07	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ C$	$I_{(AV)}$	2.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	60.0							A
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.0							V
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=100^\circ C$	$I_R$	5.0 200							$\mu A$
Typical junction capacitance (Note1)	$C_J$	45.0							pF
Typical thermal resistance	$R_{qJA}$	75.0							$^\circ C/W$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ C$

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

**Ratings And Characteristic Curves**

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

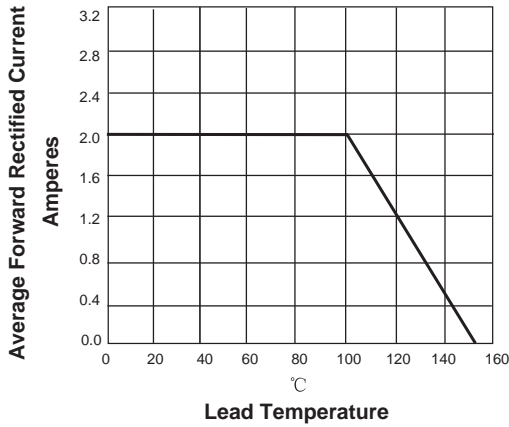


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

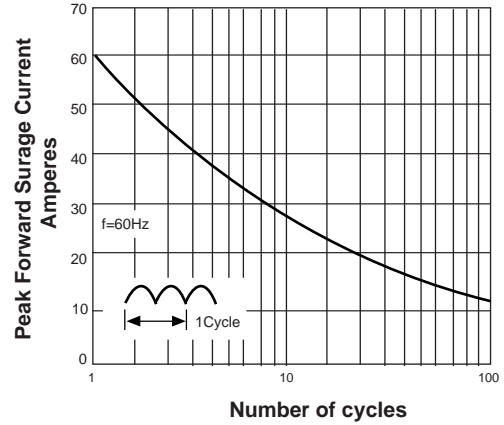


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

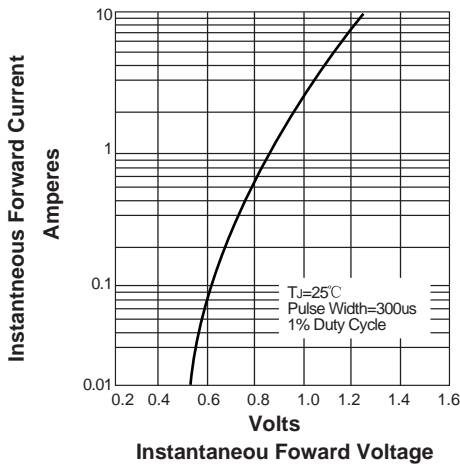
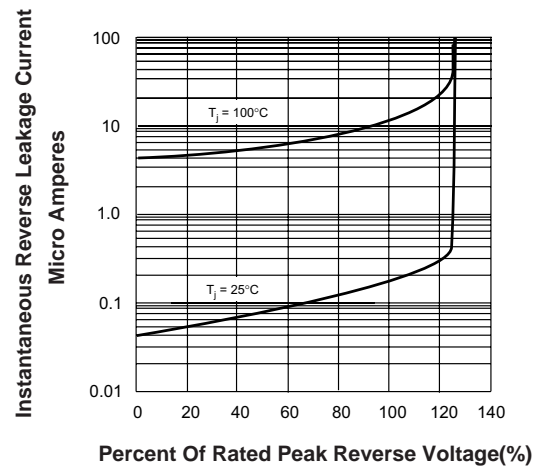
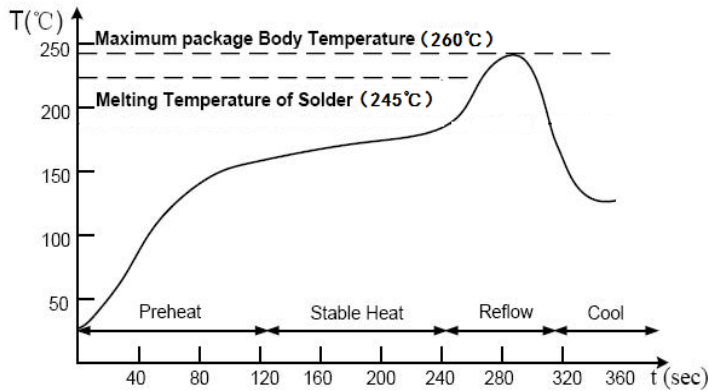


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



**Suggested Soldering Temperature Profile**

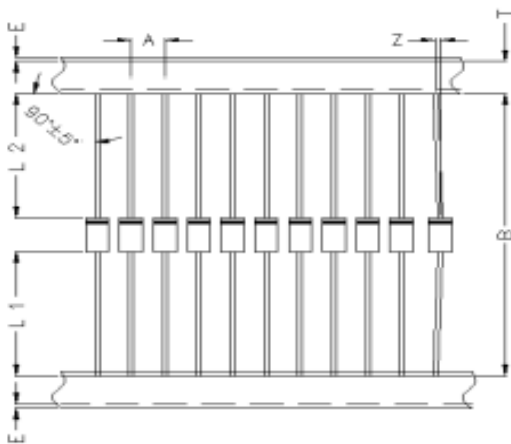


**Note**

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

**Package Information**

**Taping Specifications**



Item	Symbol	Specifications(mm)
Component Pitch	A	5.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

**Ammunition Package Specifications**

Package	Inner Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
DO - 15	255*150*75	3	420*276*312	30